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PATENT APPLICATION
THE COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

Express Mail No. EL730648668US
Attorney Docket No. 01-099

Sir:

Transmitted herewith for filing is the patent application of:
Inventor: Rongxiang Hu, Philippe Schoenborn, and Masaichi Eda
For: HIGH SELECTIVITY SiC ETC IN INTEGRATED CIRCUIT FABRICATION

Enclosed are:

Specification, Claims and Abstract.

1 Sheet of Drawings.

Combined Declaration and Power of Attorney (signed).

Assignment and Recordation Form Cover Sheet.

Nonpublication Request under 35 U.S.C. 122(b)(2)(B)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)
FOR:	NO. FILED	NO. EXTRA
BASIC FEE	//////////	//////////
TOTAL CLAIMS	*11 - 20 =	*0
INDEP CLAIMS	*2 - 3 =	*0
MULTIPLE DEPENDENT CLAIM PRESENTED		

*If the difference in Col. 1 is less than zero, enter "0" in Col. 2

SMALL
ENTITY

RATE	FEE
//////	\$355
X 9 =	\$
x 40 =	\$
+135 =	\$

TOTAL \$

OTHER THAN A
SMALL ENTITY

RATE	FEE
//////	\$710
X 18 =	\$
x 80 =	\$
+270 =	\$

TOTAL \$710.00

Please charge my Deposit Account No. 12-2252 in the amount of \$ 710.00 for filing fee. A duplicate of this sheet is attached.

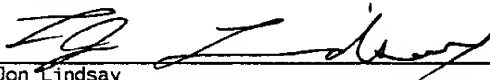
A check in the amount of \$ _____ is enclosed to cover the filing fee.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 12-2252. A duplicate copy of this sheet is enclosed.

- ☒ Any patent application processing fees under 37 C.F.R. 1.17.
- ☐ The issue fee set in 37 C.F.R. 1.18 at or before mailing of the Notice of Allowance, pursuant to 37 C.F.R. 1.311(b).
- ☒ Any filing fees under 37 C.F.R. 1.16 for presentation of extra claim.

Dated at Greenwood Village, Colorado, this 13th day of August, 2001.

Respectfully submitted,


L. Jon Lindsay
Registration No. 36,855
ATTORNEY FOR APPLICANT

JOHN R. LEY, LLC
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10971 U.S. PTO
09/28570
08/13/01

Under the Paperwork Act of 1995, no person are required to respond to a collection of information unless it displays a valid OMB control number.

**NONPUBLICATION REQUEST
UNDER
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor

Rongxiang Hu

Title

High Selectivity SiC Etch in Integrated
Circuit Fabrication

Atty Docket Number

01-099

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. This certification is made based on information and instructions received from the Assignee of the above identified application.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

8/13/01
Date


L. Jon Lindsay

Registration No. 36,855

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This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

0253660

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Rongxiang Hu, Philippe)
Schoenborn and Masaichi Eda)
Serial No.)
Filed: Concurrently Herewith)
For: HIGH SELECTIVITY SiC ETCH IN)
INTEGRATED CIRCUIT)
FABRICATION)

CERTIFICATE OF MAILING BY EXPRESS MAIL

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

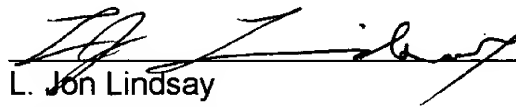
Sir:

The undersigned hereby certifies that the attached Transmittal Letter; Specification, Claims and Abstract; One (1) Sheet of Drawings; Combined Declaration and Power of Attorney (signed); Assignment and Recordation Form Cover Sheet; Nonpublication Request under 35 U.S.C. 122(b)(2)(B)(i); Certificate of Mailing by Express Mail; and Return Card, relating to the above application, were deposited as "Express Mail," Mailing Label No. EL730648668, with the United States Postal Service, addressed to The Commissioner of Patents and Trademarks, Washington, D.C. 20231, on this 13th day of August, 2001.

8/13/01
Date

8/13/01
Date


Mailer


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